



PRESS RELEASE

BE Semiconductor Industries N.V. Announces Order for 26 Hybrid Bonding Systems

Duiven, the Netherlands, May 9, 2024 - BE Semiconductor Industries N.V. (the "Company" or "Besì") (Euronext Amsterdam: BESI; OTC markets: BESIY), a leading manufacturer of assembly equipment for the semiconductor industry, today announced the receipt of an order for 26 hybrid bonding systems from a leading semiconductor logic manufacturer. The order is for Besì's latest generation system incorporating 100 nm placement accuracy and is scheduled for delivery in Q4-24 and Q1-25. Besì anticipates receiving additional hybrid bonding orders from other customers in Q2-24 as well.

Richard W. Blickman, President and Chief Executive Officer of Besì, commented:

"The receipt of this significant order highlights the commitment by a second leading logic manufacturer to adopt hybrid bonding assembly technology for their most advanced data center applications. It also helps confirm the favorable long-term prospects and roadmap anticipated for Besì's hybrid bonding systems in next generation AI related logic, memory and consumer related computing applications over the next decade."

About Besì

Besì is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries offering high levels of accuracy, productivity and reliability at a low cost of ownership. The Company develops leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, cloud server, computing, automotive, industrial, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Besì's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.besi.com.

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